

ABSTRACT

Method and Apparatus for Decapping Integrated Circuit Packages

The invention relates to a method and apparatus for decapping
5 integrated circuit packages. The invention involves irradiating an IC
package with laser radiation, typically in the UV - IR spectra and of
short pulse duration. The irradiation results in ablation of the
molding compound. The invention also provides real-time monitoring
and process control of the decapping process and fluid-flow removal
10 of ablation debris. Using the invention, decapping can be performed
without causing damage to the internal IC structure. Furthermore,
decapping in a liquid can prevent oxidisation of the molding compound
by ambient air.

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(Figure 2)

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